

Figure 1

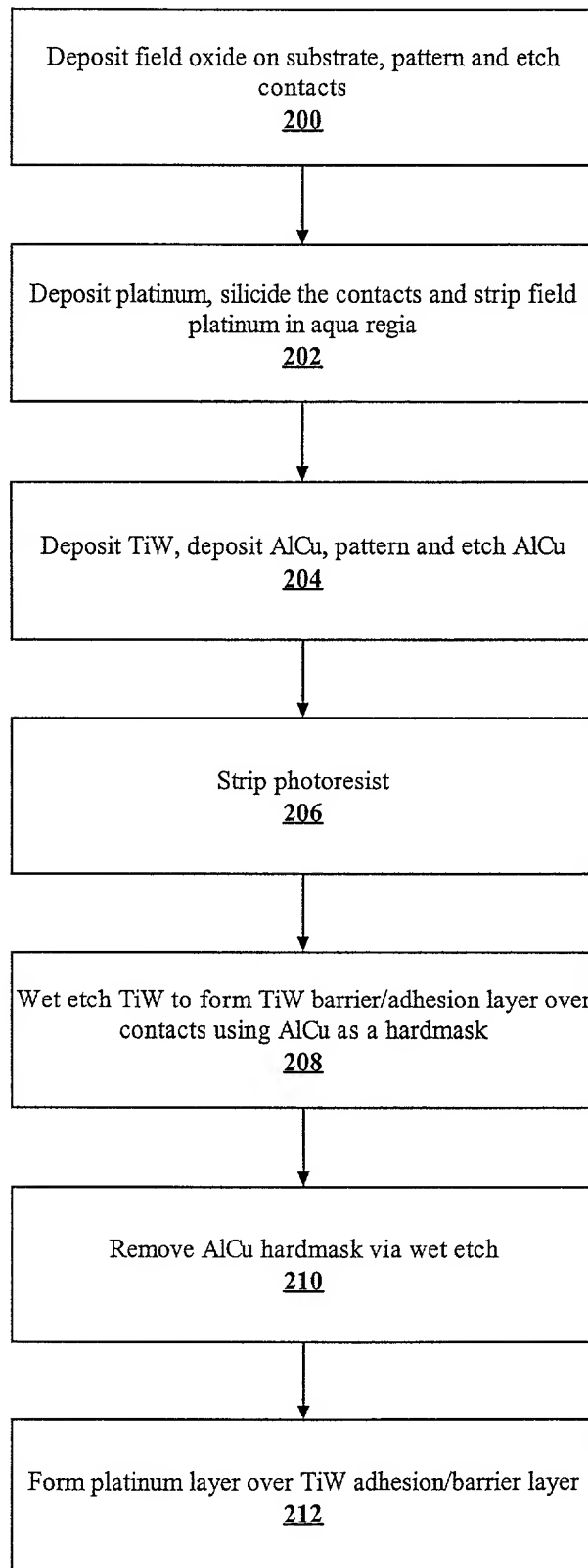


Figure 2

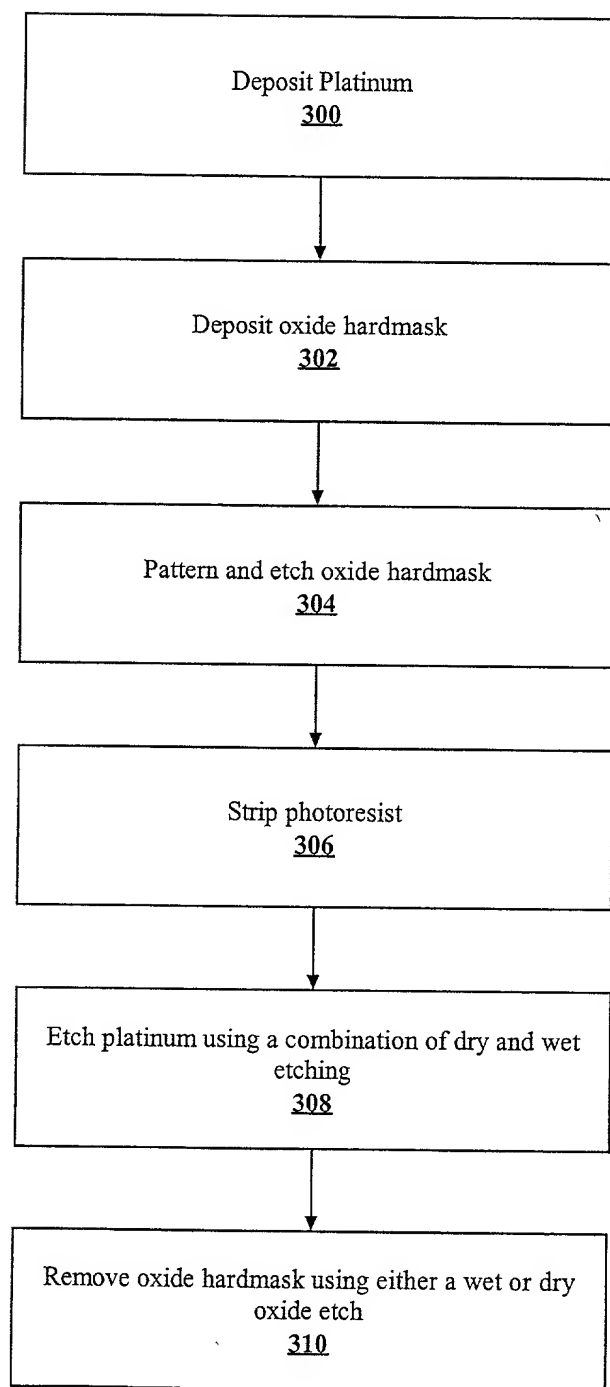


Figure 3

Pattern and etch contacts

Strip resist

Deposit Platinum and silicide the contacts

Strip field Pt in aqua regia

402
Field oxide

404
Pt_x-Si contact

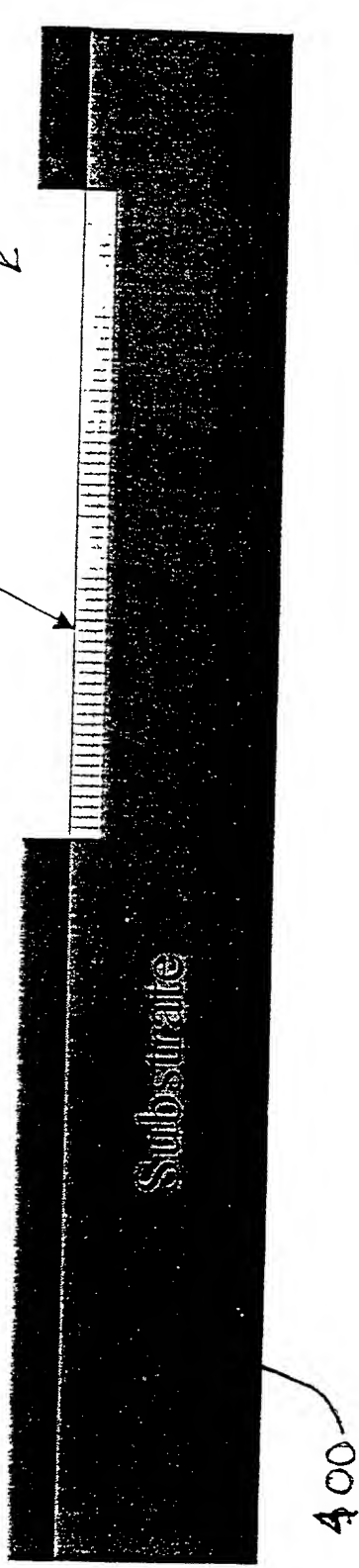


Figure 4a

207710-600000T

(2)

Deposit TiW

Pattern and etch TiW barrier over contacts

Strip resist

406
TiW

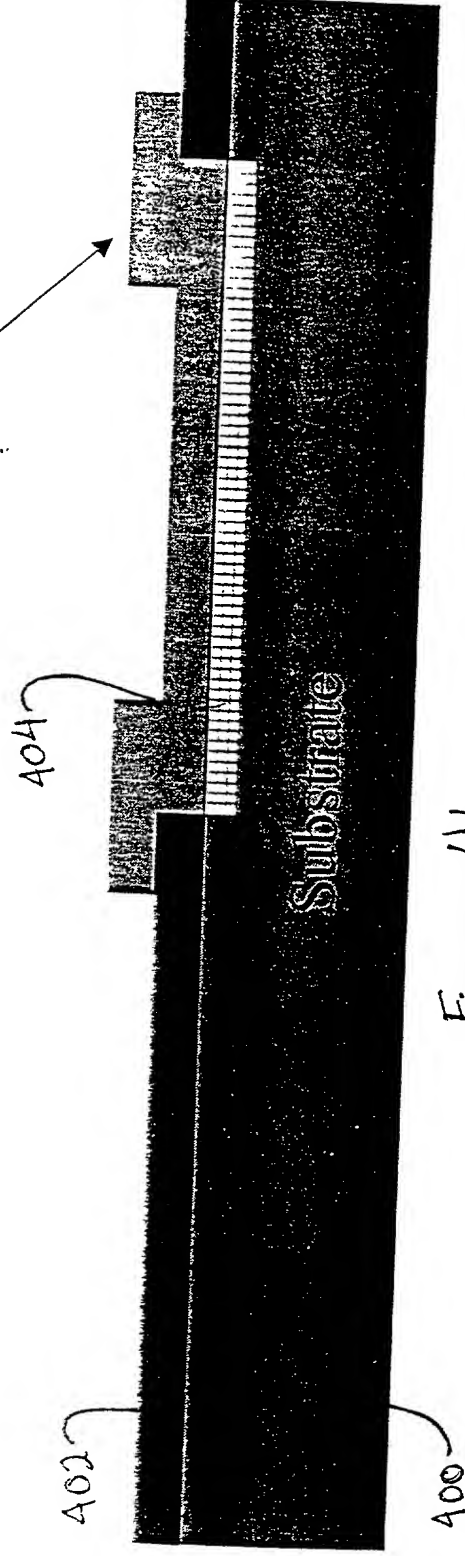


Figure 4b

Note: contingency field on reticle for TiW adhesion layer under all interconnect

- Deposit Platinum for interconnect
- Deposit oxide for hardmask
- Pattern and etch hardmask
- Strip resist

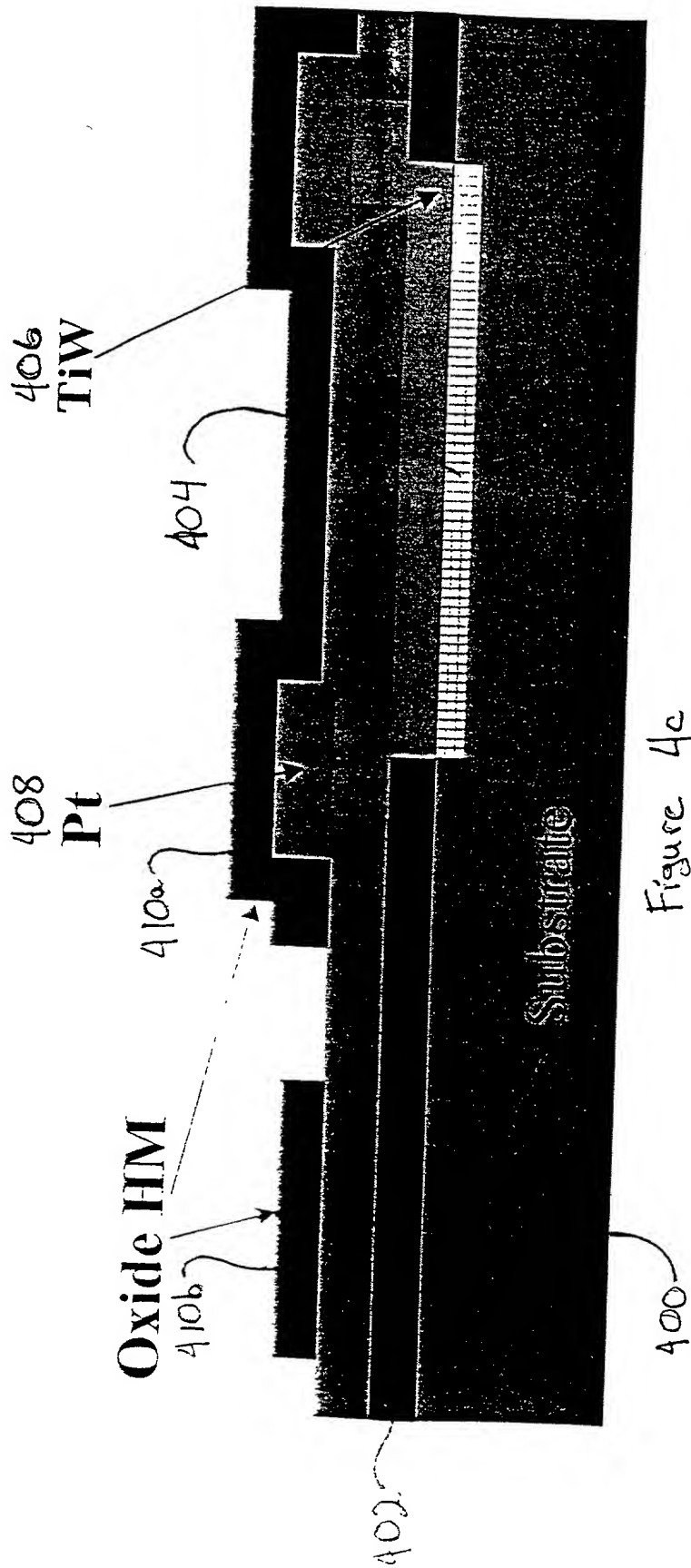


Figure 4c

Etch Platinum for interconnect

Remove hardmask

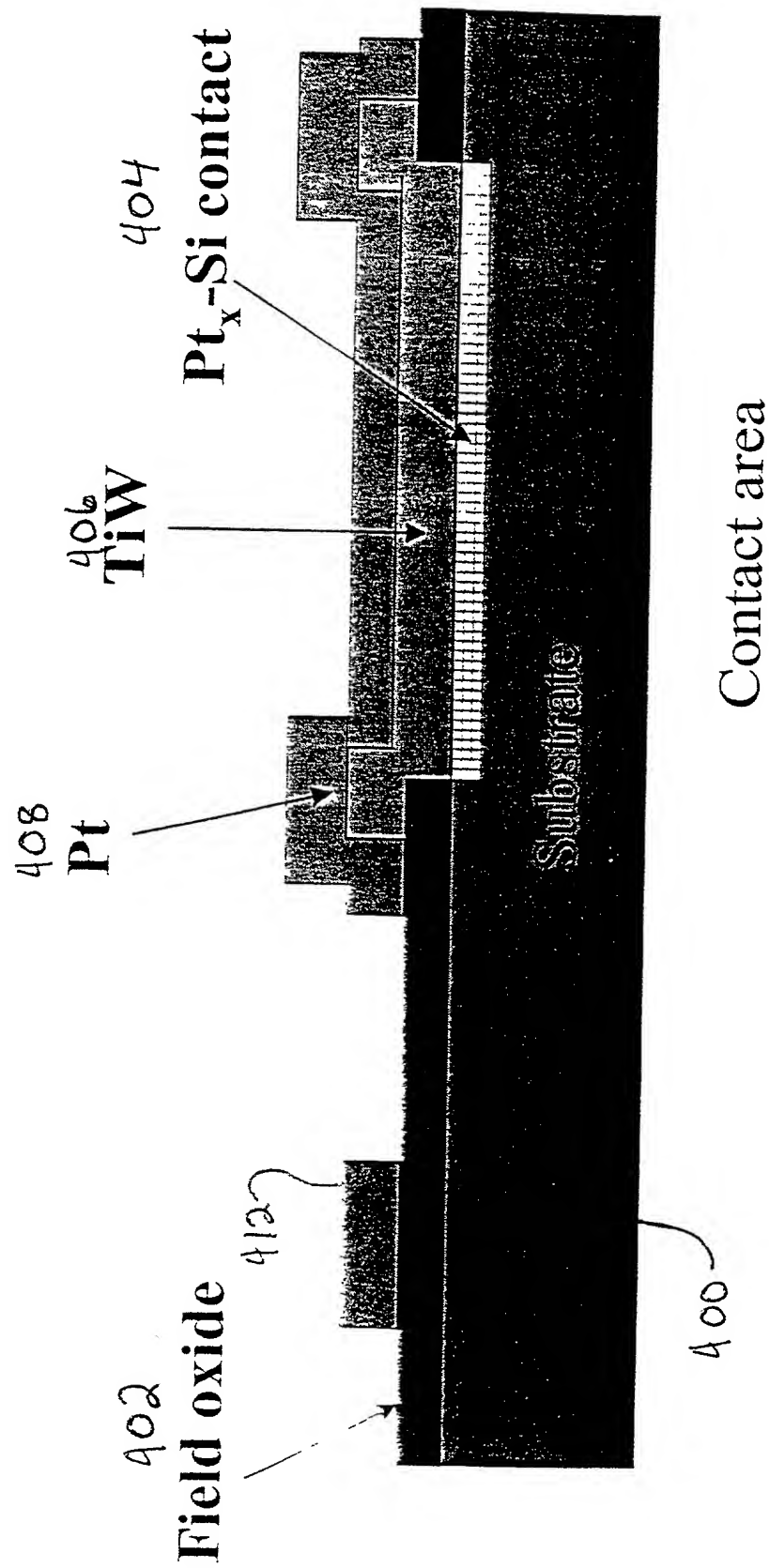


Figure 4d

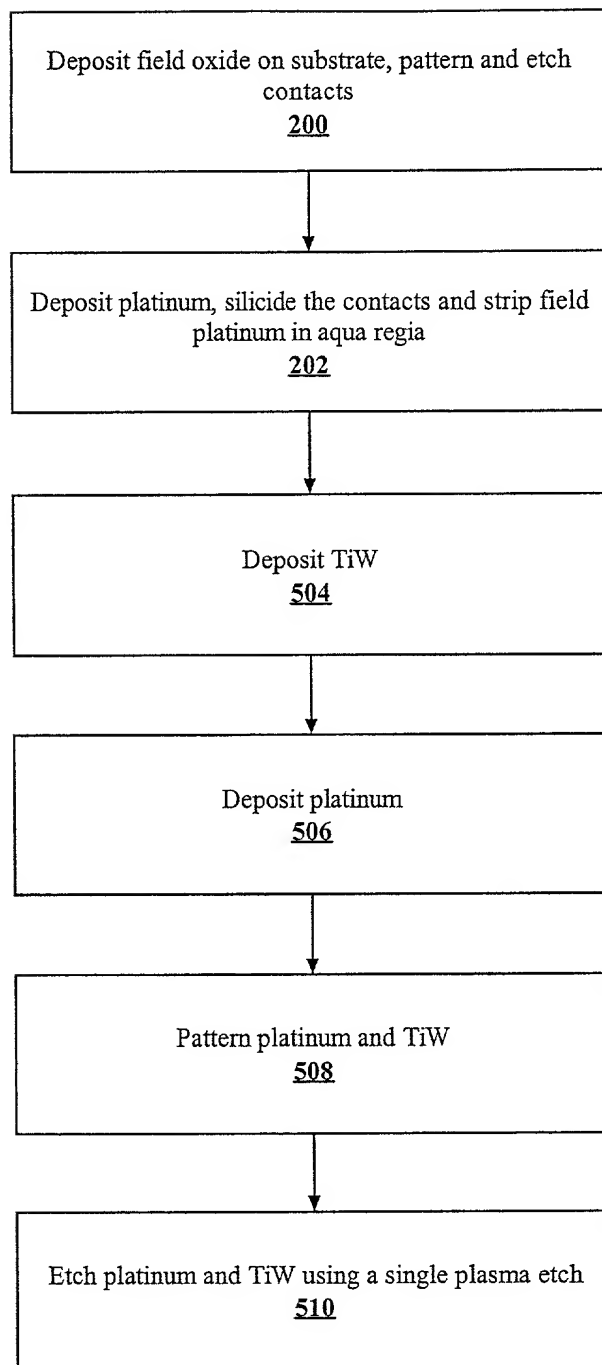


Figure 5

207770" 6004400T

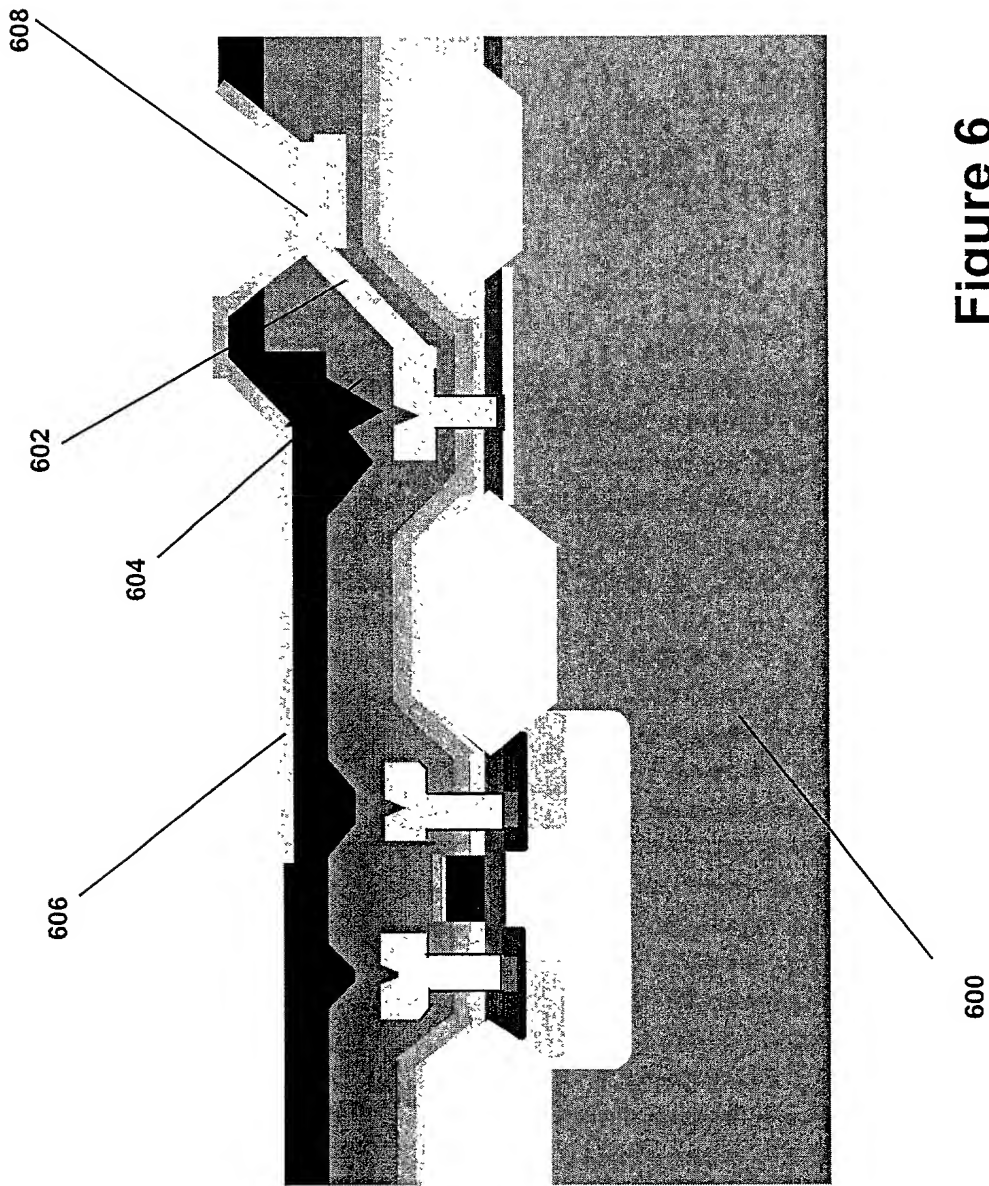


Figure 6